

Future trends of 3D silicon sensors

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Vertex detectors for the next LHC experiments upgrades will need to have low mass while at the same time be radiation hard and with sufficient granularity to fulfill the physics challenges of the next decade. Based on the gained experience with 3D silicon sensors for the ATLAS IBL project and the ongoing developments on light materials, interconnectivity and cooling, this paper will discuss possible solutions to these requirements.

Author: Dr DA VIA, Cinzia (University of Manchester (GB))

Presenter: Dr DA VIA, Cinzia (University of Manchester (GB))

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